“Innovative technologies introduction impacts favorably the LED packaging materials market”, says Yole Développement

LED Packaging Technology and Market Trends 2014 report

LYON, France – September 30, 2014 – The LED packaging industry is moving toward further cost reduction and new technologies including Flip Chip and Chip Scale Package (CSP), says Yole Développement (Yole) in its latest report on packaging for LED: LED Packaging Technology and Market Trends 2014. These market and technology trends directly impact the LED & advanced packaging industry and its supply chain, especially at the material and equipment levels: whereas the equipment market enters in an infernal cycle, the materials market for LED packaging confirms its growth...

Under this new report, Yole proposes a detailed analysis of each LED packaging process step including of Flip Chip and CSP technologies. The market research and strategy consulting company highlights the recent trends in LED packaging, and the importance of cost reduction in this industry. Market metrics, from 2010 to 2019 are also deeply analyzed by Yole, at all levels of the supply chain.

“The LED packaging materials market, including packaging substrates, phosphors, encapsulation and primary optic materials, ESD (Electrostatic Discharge) protection diodes, will grow by a factor x1.5 during the period 2014-2019”, announces Pars Mukish, Activity Leader, LED & Compound Semiconductors at Yole Développement.

![LED packaging material revenue graph](image)
For immediate release:

With the general lighting market triggered, LED packaging needs materials in agreement with the requirements of applications. Regarding packaging substrates, the high power density of devices induces the use of ceramic substrates. “The ceramic substrates market will grow from nearly $400 million in 2013 to $700 million in 2019”, estimates Dr Eric Virey, Senior Analyst, Yole Développement.

Encapsulant and optic materials will follow the same trend. According to Yole’s analysis, this market is about $300 million in 2013 and should reach to $700 million in 2019, driven mostly by the increased use of silicone material. Indeed silicon material offers better reliability and lifetime than traditional epoxy material.

At the phosphor level, the expiration of key “yellow phosphor” patents in the area from 2017 will increase adoption of Yttrium Aluminium Garnet (YAG) material and it will also increase competition, ultimately leading to further price decrease. But even with an average selling price (ASP) decreasing, market will grow from a size of nearly $600 million in 2013 to $900 million in 2019.

This report represents a comprehensive overview of all aspects of LED packaging. It describes each step of the packaging process flow, discusses the associated technological breakthroughs, provides a summary of key players, and much more!

More information about Yole Développement LED Packaging report is available on www.i-micronews.com, LED section.

About LED Packaging Technology and Market Trends 2014 report

Authors:

Pars Mukish holds a master’s degree in Materials Science & Polymers and a master’s degree in Innovation & Technology Management (EM Lyon – France). He works at Yole Développement as Senior Market and Technology Analyst in the fields of LED, Lighting Technologies, Compound Semiconductors and OLEDs to carry out technical, economic and marketing analysis. Previously, he has worked as Marketing & Techno-Economic Analyst at the CEA (French Research Center).

Eric Virey holds a PhD in Optoelectronics from the national Polytechnic Institute of Grenoble. In the last 12 years, he’s held various R&D, engineering, manufacturing and marketing positions with Saint-Gobain. Most recently, he was Market Manager at Saint-Gobain Crystals, in charge of Sapphire and Optoelectronic products.

Publication date: October 2014

Companies cited in this report:

For immediate release:

Group, Evident Technologies, Excellence, Fangda, Fittech, Formosa Epitaxy, Friatec, GE, Gia Tzoong, Golden Valley, Han’s Laser, Harvatek, Hauman, Heesung, Heptagon, Hilight, Holy and more...

- Rates: Euros 5,990.00 (Full report - Multi user license) – Euros 2,990 (Executive Summary) – For special offers and the price in dollars, please contact David Jourdan (jourdan@yole.fr or +33 472 83 01 90).


Founded in 1998, Yole Développement has grown to become a group of companies providing marketing, technology and strategy consulting, media in addition to corporate finance services. With a strong focus on emerging applications using silicon and/or micro manufacturing, Yole Développement group has expanded to include more than 50 collaborators worldwide covering MEMS, Compound Semiconductors, LED, Image Sensors, Optoelectronics, Microfluidics & Medical, Photovoltaics, Advanced Packaging, Manufacturing, Nanomaterials and Power Electronics. The group supports industrial companies, investors and R&D organizations worldwide to help them understand markets and follow technology trends to develop their business.

CONSULTING
- Market data & research, marketing analysis
- Technology analysis
- Reverse engineering & costing services
- Strategy consulting
- Patent analysis

More information on www.yole.fr

REPORTS
- Collection of technology & market reports
- Manufacturing cost simulation tools
- Component reverse engineering & costing analysis
- Patent investigation

More information on www.i-micronews.com

FINANCIAL SERVICES
- Mergers & Acquisitions
- Due diligence
- Fundraising
- Coaching of emerging companies
- IP portfolio management & optimization

More information on www.yolefinance.com

MEDIA & EVENTS
- i-Micronews.com, online disruptive technologies website
- @Micronews, weekly e-newsletter
- Technology Magazines dedicated to MEMS, Advanced Packaging, LED and Power Electronics
- Communication & webcasts services
- Events: Yole Seminars, Market Briefings

More information on www.i-micronews.com

CONTACTS
For more information about:
- Consulting Services: Jean-Christophe Eloy (eloy@yole.fr)
- Financial Services: Géraldine Andrieux-Gustin (Andrieux@yole.fr)
- Reports business: David Jourdan (jourdan@yole.fr)
- Corporate Communication: Sandrine Leroy (leroy@yole.fr)

###